BLP10H603

Broadband LDMOS driver transistor

Rev. 1 — 2 October 2014 Product data sheet

1. Product profile

1.1 General description

A 2.5 W plastic LDMOS power transistor for broadcast transmitter and ISM applications at frequencies from HF to 1400 MHz.

Table 1. Application performance

Test signal	f	V_{DS}	P_L	G_p	η_D
	(MHz)	(V)	(W)	(dB)	(%)
CW	860	50	2.5	22.8	62

1.2 Features and benefits

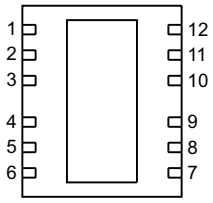
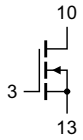
- Easy power control
- Integrated ESD protection
- Excellent ruggedness
- High efficiency
- Excellent thermal stability
- Designed for broadband operation (HF to 1400 MHz)
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

1.3 Applications

- Industrial, scientific and medical applications
- Broadcast transmitter applications

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1, 2, 4, 5, 6, 7, 8, 9, 11, 12	n.c.	 Transparent top view	 aaa-012010
3	gate1		
10	drain1		
13	source [1]		

[1] Connected to flange.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BLP10H603	HVSON12	plastic thermal enhanced very thin small outline package; no leads; 12 terminals; body 5 × 6 × 0.85 mm	SOT1352-1

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage		-	104	V
V_{GS}	gate-source voltage		−6	+11	V
T_{stg}	storage temperature		−65	+150	°C
T_j	junction temperature		-	150	°C

5. Recommended operating conditions

See application note *AN11520* for more details.

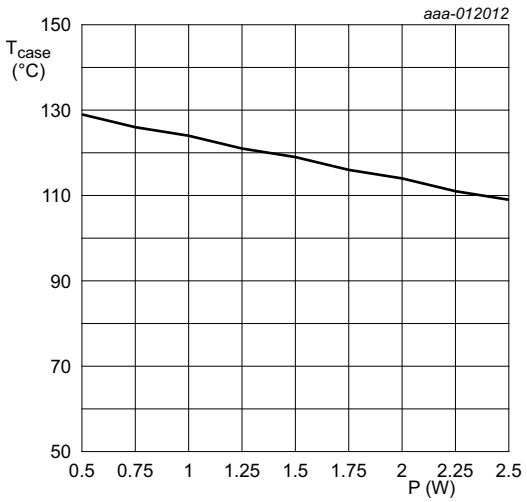


Fig 1. Recommended operating area; case temperature as a function of power dissipation

6. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	T_{case} = 80 °C; P_L = 2.5 W [1]	9.9	K/W

[1] $R_{th(j-c)}$ is measured under RF conditions

7. Characteristics

Table 6. DC characteristics

T_j = 25 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	V_{GS} = 0 V; I_D = 0.03 mA	104	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	V_{DS} = 10 V; I_D = 3 mA	1.25	1.65	2.25	V
V_{GSq}	gate-source quiescent voltage	V_{DS} = 50 V; I_D = 15 mA	1.3	1.73	2.15	V
I_{DSS}	drain leakage current	V_{GS} = 0 V; V_{DS} = 50 V	-	-	1.4	μA
I_{DSX}	drain cut-off current	V_{GS} = $V_{GS(th)}$ + 3.75 V; V_{DS} = 10 V	-	0.5	-	A
I_{GSS}	gate leakage current	V_{GS} = 11 V; V_{DS} = 0 V	-	-	140	nA
$R_{DS(on)}$	drain-source on-state resistance	V_{GS} = $V_{GS(th)}$ + 3.75 V; I_D = 105 mA	-	9	-	Ω

Table 7. AC characteristics

T_j = 25 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C_{rs}	feedback capacitance	V_{GS} = 0 V; V_{DS} = 50 V; f = 1 MHz	-	0.03	-	pF
C_{iss}	input capacitance	V_{GS} = 0 V; V_{DS} = 0 V; f = 1 MHz	-	3.4	-	pF
C_{oss}	output capacitance	V_{GS} = 0 V; V_{DS} = 50 V; f = 1 MHz	-	1.12	-	pF

Table 8. RF characteristics

Test signal: pulsed CW; f = 860 MHz; RF performance at V_{DS} = 50 V; I_{Dq} = 15 mA; t_p = 50 µs; δ = 10 %; T_{case} = 25 °C; unless otherwise specified, in a class-AB production test circuit [1].

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
G_p	power gain	P_L = 2.5 W	21.4	22.8	25.5	dB
η_D	drain efficiency	P_L = 2.5 W	60	62	-	%

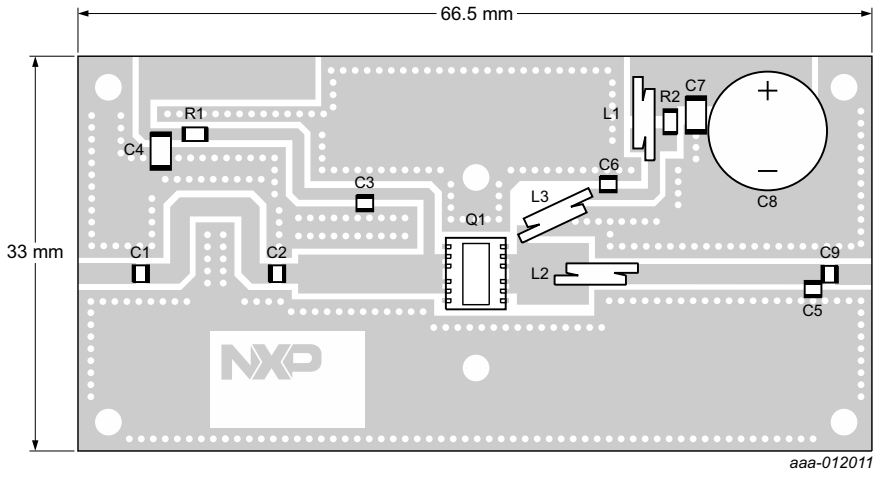
[1] The industrial test method is performed on special hardware to accommodate the requirements of production. The test results in this table are correlated to correspond with a performance in the application.

8. Test information

8.1 Ruggedness in class-AB operation

The BLP10H603 is capable of withstanding a load mismatch corresponding to VSWR = 35 : 1 through all phases under the following conditions: V_{DS} = 50 V; I_{Dq} = 15 mA; P_L = 2.5 W; f = 860 MHz.

8.2 Test circuit



Printed-Circuit Board (PCB): Rogers RO4350; ε_r = 3.48; height = 0.762 mm; thickness copper plating = 35 µm.

See Table 9 for a list of components.

Fig 2. Component layout

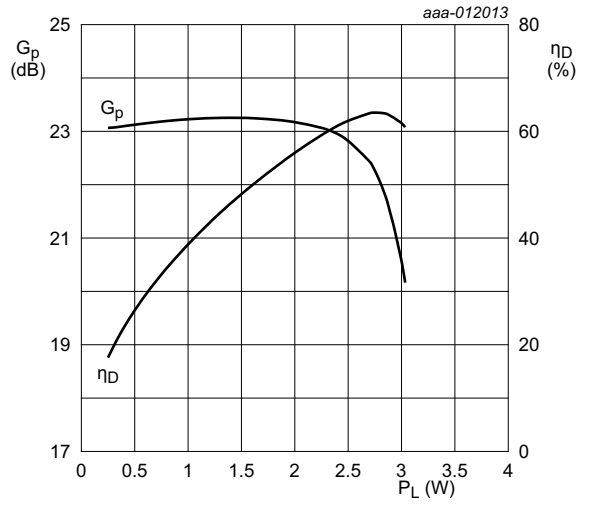
Table 9. List of components

See Figure 2 for component layout.

Component	Description	Value		Remarks
C1, C3, C6, C9	multilayer ceramic chip capacitor	100 pF	[1]	
C2	multilayer ceramic chip capacitor	3.9 pF	[1]	
C4	multilayer ceramic chip capacitor	1 μF, 25 V		Murata GRM31MR71E105KA01L
C5	multilayer ceramic chip capacitor	4.7 pF	[1]	
C7	multilayer ceramic chip capacitor	1 μF, 50 V		Murata GRM32RR71H105KA01L
C8	electrolytic capacitor	220 μF, 63 V		
L1	wire inductor, 0.8 mm copper wire	2 turn, D = 3 mm		
L2	wire inductor, 0.8 mm copper wire	2 turn, D = 2.7 mm		
L3	wire inductor, 0.8 mm copper wire	2 turn, D = 3 mm		
R1	resistor	0 Ω		SMD 0805
R2	resistor	10 Ω		SMD 0805
Q1	transistor	-		BLP10H603

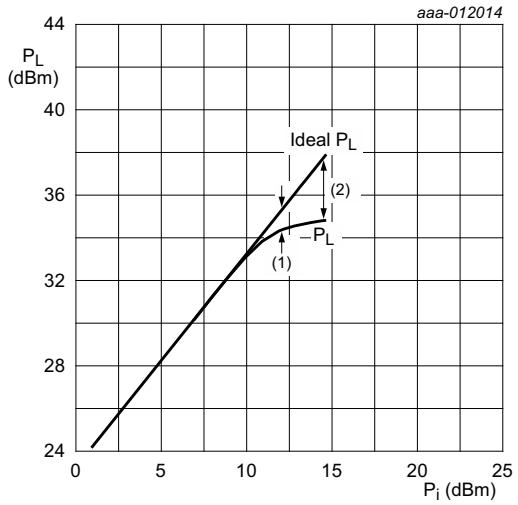
[1] American Technical Ceramics type 100A or capacitor of same quality.

8.3 Graphical data



V_{DS} = 50 V; I_{Dq} = 15 mA; f = 860 MHz.

Fig 3. Power gain and drain efficiency as function of output power; typical values

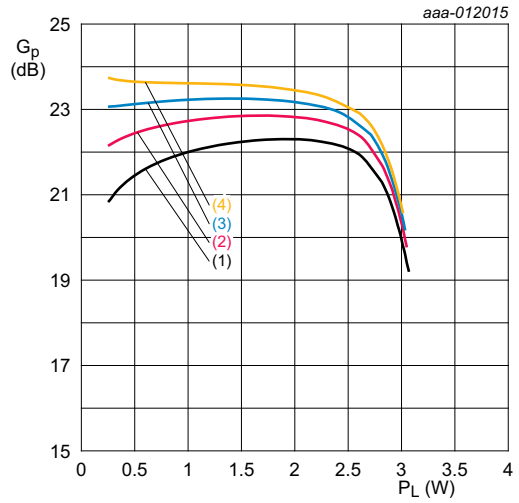


V_{DS} = 50 V; I_{Dq} = 15 mA; f = 860 MHz.

(1) $P_{L(1dB)}$ = 34.4 dBm (2.8 W)

(2) $P_{L(3dB)}$ = 34.8 dBm (3.0 W)

Fig 4. Output power as a function of input power; typical values



V_{DS} = 50 V; f = 860 MHz.

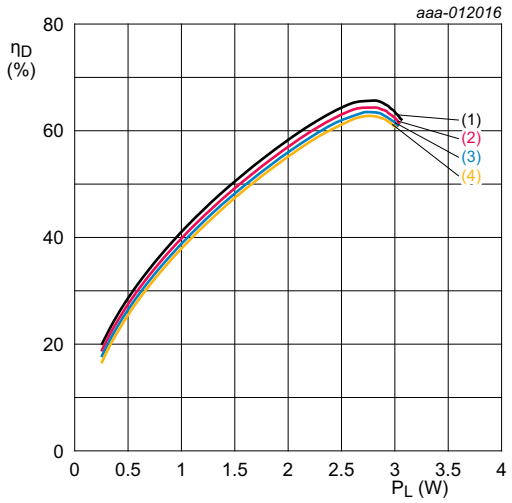
(1) I_{Dq} = 5 mA

(2) I_{Dq} = 10 mA

(3) I_{Dq} = 15 mA

(4) I_{Dq} = 20 mA

Fig 5. Power gain as a function of output power; typical values



V_{DS} = 50 V; f = 860 MHz.

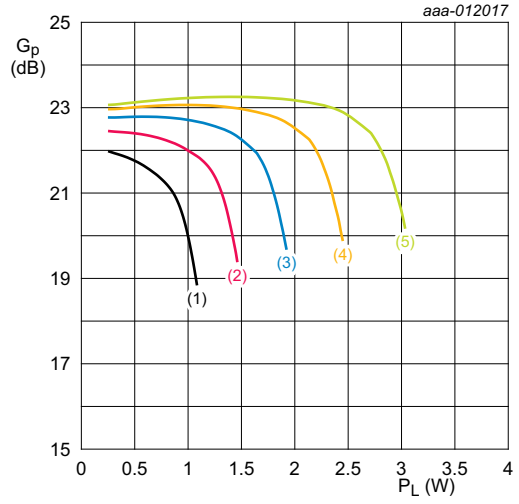
(1) I_{Dq} = 5 mA

(2) I_{Dq} = 10 mA

(3) I_{Dq} = 15 mA

(4) I_{Dq} = 20 mA

Fig 6. Drain efficiency as a function of output power; typical values



I_{Dq} = 15 mA; f = 860 MHz.

(1) V_{DS} = 30 V

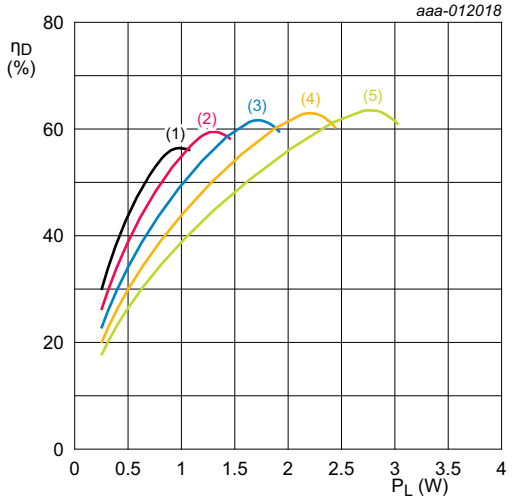
(2) V_{DS} = 35 V

(3) V_{DS} = 40 V

(4) V_{DS} = 45 V

(5) V_{DS} = 50 V

Fig 7. Power gain as a function of output power; typical values



I_{Dq} = 15 mA; f = 860 MHz.

(1) V_{DS} = 30 V

(2) V_{DS} = 35 V

(3) V_{DS} = 40 V

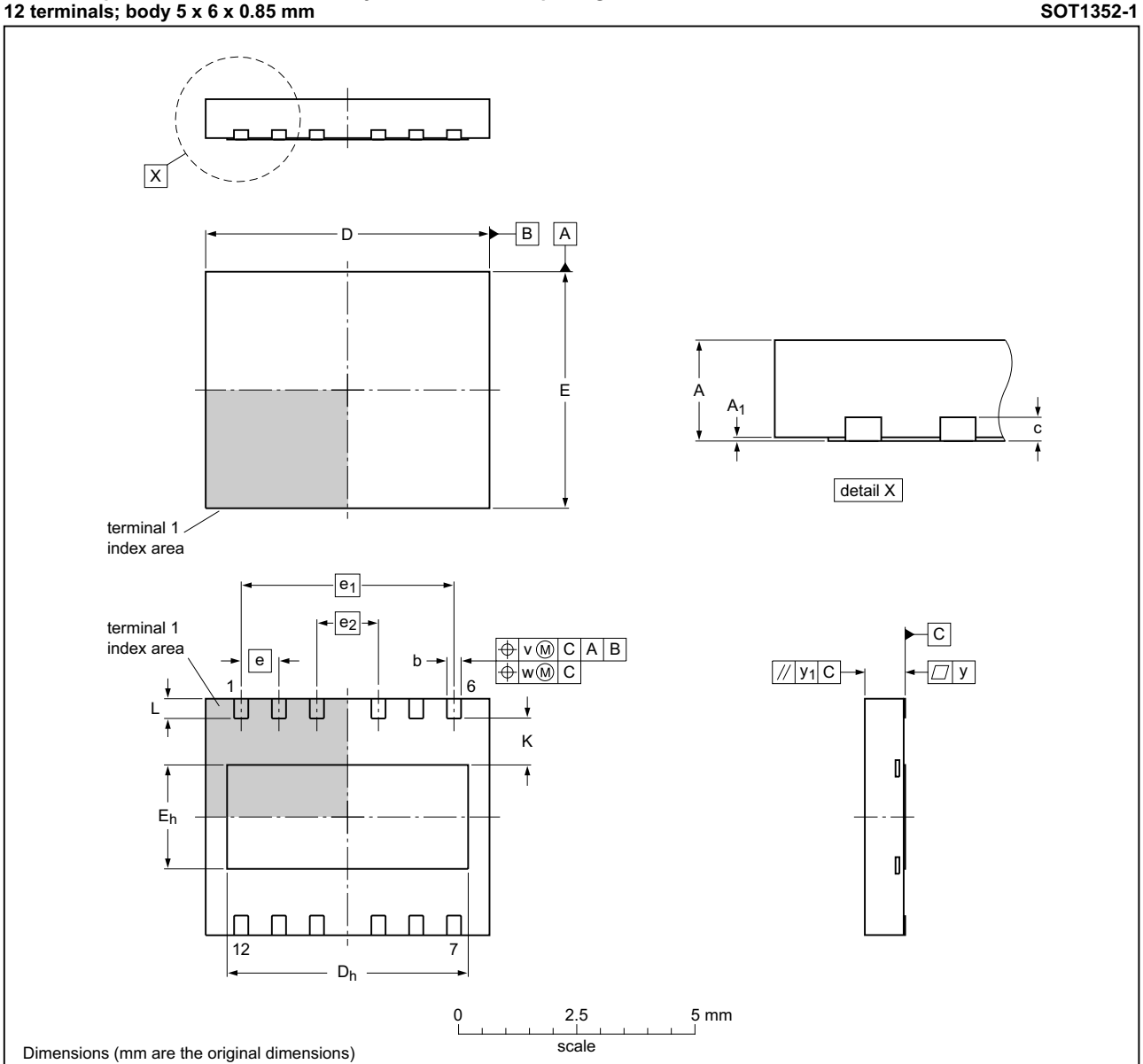
(4) V_{DS} = 45 V

(5) V_{DS} = 50 V

Fig 8. Drain efficiency as a function of output power; typical values

9. Package outline

HVSON12: plastic thermal enhanced very thin small outline package; no leads; 12 terminals; body 5 x 6 x 0.85 mm **SOT1352-1**



Dimensions (mm are the original dimensions)

Unit		A	A_1	b	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	e_2	K	L	v	w	y	y_1
	max	1.00	0.05	0.35		6.1	5.2	5.1	2.3					0.5				
mm	nom	0.85	0.03	0.30	0.2	6.0	5.1	5.0	2.2	0.8	4.5	1.3		0.4	0.1	0.05	0.05	0.1
	min	0.80	0.00	0.25		5.9	5.0	4.9	2.1				1.0	0.3				

Note
1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot1352-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1352-1	- - -	MO-229	- - -			~~13-03-26~~ 13-07-16

Fig 9. Package outline SOT1352-1 (HVSON12)

10. Handling information

CAUTION

This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

11. Abbreviations

Table 10. Abbreviations

Acronym	Description
CW	Continuous Wave
ESD	ElectroStatic Discharge
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
HF	High Frequency
ISM	Industrial, Scientific and Medical
SMD	Surface Mounted Device
VSWR	Voltage Standing-Wave Ratio

12. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLP10H603 v.1	20141002	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

13.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between NXP Semiconductors and its customer, unless NXP Semiconductors and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the NXP Semiconductors product is deemed to offer functions and qualities beyond those described in the Product data sheet.

13.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nxp.com/profile/terms, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Non-automotive qualified products — Unless this data sheet expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

Translations — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

13.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

14. Contact information

For more information, please visit: **http://www.nxp.com**

For sales office addresses, please send an email to: **salesaddresses@nxp.com**

15. Contents

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 2 October 2014
Document identifier: BLP10H603

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001
Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:
moschip.ru
moschip.ru_4
moschip.ru_6
moschip.ru_9